

# In Brief: Winbond buys laser system for chip plant

July 7 2006

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U.S. laser producer ESI has received an order from Winbond Electronics for a semiconductor link processing system to be used in Winbond's 300mm fab plant in Taiwan.

ESI said that the Model 9830 laser-based system will be used by Winbond for DRAM (dynamic random-access memory) repair applications as part of its volume production of high-performance memory chips.

"This latest order illustrates the continued broad adoption of our laser technology by the world's leading DRAM manufacturers," boasted ESI's Paul Kirby.

Winbond products are used in Flash memory and other semiconductor applications.

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